

# Design & Technology

## AQA A-Level

# Paper and board forming processes

### Materials required for questions

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- Pencil
- Rubber
- Calculator

### Instructions

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- Use black ink or ball-point pen
- Try answer all questions
- Use the space provided to answer questions
- Calculators can be used if necessary
- For the multiple choice questions, circle your answer

### Advice

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- Marks for each question are in brackets
- Read each question fully
- Try to answer every question
- Don't spend too much time on one question

# Good luck!

**Q1.** What is the primary purpose of die cutting in paper packaging?

- A** Adding decorative colours
- B** Cutting precise shapes using a metal die
- C** Increasing material thickness

**Q2.** Which process uses a high-powered beam to create intricate designs in paper?

- A** Creasing
- B** Bending
- C** Laser cutting

**Q3.** Why is creasing applied to paper or board before folding?

- A** To weaken the fibres for easier bending
- B** To add waterproof coatings
- C** To enhance print quality

**Q4.** What is a key advantage of laser cutting over traditional die cutting?

- A** Lower initial setup costs for small batches
- B** Faster production of large quantities
- C** No need for skilled operators

**Q5. Describe the process of die cutting (6 marks)**

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## Answers

**Q1.** B

**Q2.** C

**Q3.** A

**Q4.** A

**Q5.**

Die production

- A thin steel cutter blade is folded and shaped into the desired profile or shape.
- Creasing rules and perforations can be incorporated into the die depending on the required output.
- These blades are mounted into a substrate board/cylinder which maintains the shape and alignment of the die.

Mounting die in machine

- The die is mounted into a pressing machine that may be manual or hydraulic.
- The die can either be flat or cylindrical.

Feed card into machine

- Card blanks are fed into the press either in batches or continuously.

Card secured in place

- The substrate to be cut is located in the machine, often using locator guides to ensure the correct alignment.

Pressure applied to card

- The die is forced through the material and the waste material and die cut pattern is removed.

Pressure removed and card ejected

- A soft rubber support surrounds the die. This is compressed when the die is used and ejects the cut material when the force is removed.

